

CUSTOMER	
CUST. PART NO.	
CUST. DOC. REV.	
DESCRIPTION	POWER CHOKE(RoHS+H.F.)
SAMPLE LOT NO.	
PART NO.	CSMS0840D-XXXX-LRH
DOC. REV.	
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Once you approve this part, please sign a	nd return this page to the following marked location.
PASSI	VE SYSTEM ALLIANCE
Customer Signature:	Date:
	0° 52
This part currently development section.	Production line can produce this series of products.
SPEPING	Dielecti
Salas Office Headsworther	FI ECTDICS CO.
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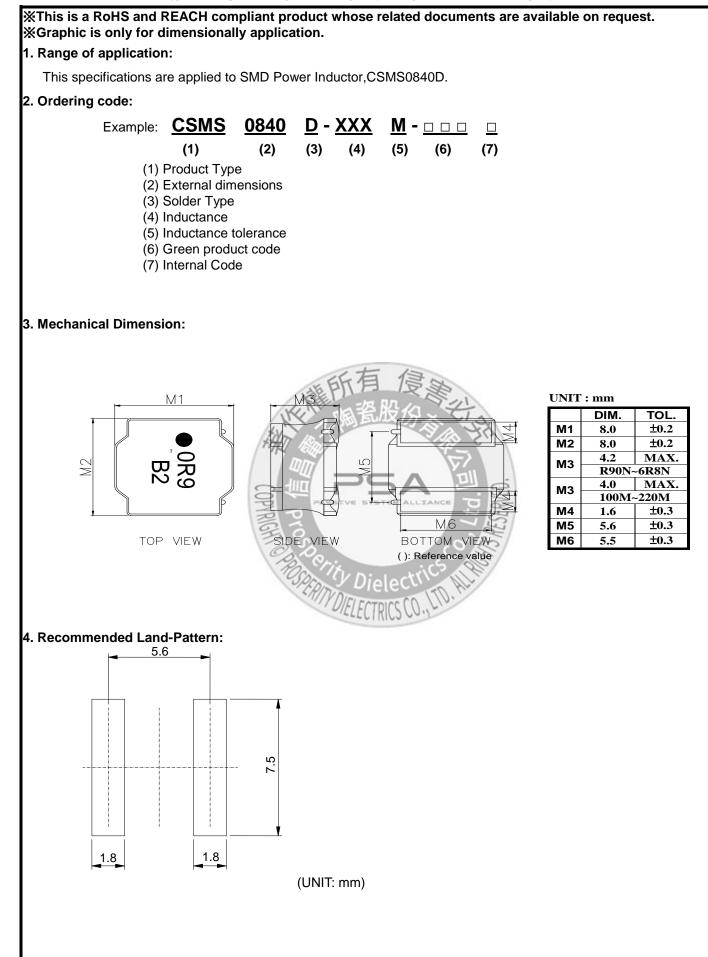
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CUSTOMER		CUSTOMER P/N	REV.	SPL. LOT NO.		
PART NAME POWER CH((ROHS+H.		PART NO. CSMS0840D-XXXX-LRH	REV.	DATE OF ISSUE	Q'TY O	PCS
]	ENG	INEERING CHAN	GE NO	TICE - REC	ORD	
REVISION NO.		REVISION DESCRIPTIO	DN	AUTHOR	DATE	REMARK
		COPYRIGHT OF THE PROSPECTIVE SYS	侵害 股份有限 STEM ALLIANCE	North Steamen.		
		CRITOIELECT	electric RICS CO., LTD			



5. Electrical Characteristics:

	Nominal Inductance Ind	Inductance	DC Resistance	Rated Current (mA)		Self-resonant Frequency
Part number	(uH) @100KHz	Tolerance	(Ω) ±20%	Saturation Current Idc1	Temperature Rise Current Idc2	Min (MHz)
CSMS0840D-R90N-LRH	0.9	±30%	0.006	13000	7800	85
CSMS0840D-1R4N-LRH	1.4	±30%	0.007	10000	7000	63
CSMS0840D-2R0N-LRH	2.0	±30%	0.009	8100	6300	50
CSMS0840D-3R6N-LRH	3.6	±30%	0.015	6400	4900	34
CSMS0840D-4R7N-LRH	4.7	±30%	0.018	5400	4100	30
CSMS0840D-6R8N-LRH	6.8	±30%	0.025	4400	3700	24
CSMS0840D-100M-LRH	10	±20%	0.034	3800	3100	22
CSMS0840D-150M-LRH	15	±20%	0.050	2900	2400	16
CSMS0840D-220M-LRH	22	±20%	0.066	2400	2200	13
CSMS0840D-330M-LRH	33	±20%	0.100	2000	1700	12
CSMS0840D-470M-LRH	47	±20%	0.140	1500	1500	8
CSMS0840D-101M-LRH	100	±20%	0.280	1100	1000	6

1. Test Frequency: 100KHz

2. Test Equipment:

Inductance: Chroma3302+1320+16502. or equivalent. DCR: Chroma16502 or equivalent.

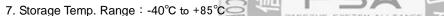
SRF: HP4291B or equivalent.

3. Saturation Current Idc1: The value of current causes a 30% inductance reduction from initial value.

4. Temperature rise current ldc2: The value of current causes a $40^\circ C$ temperature rise.

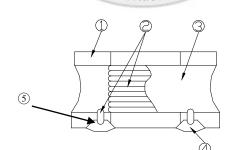
5. Rated Current: Either Idc1 or Idc2 whichever is smaller.

6. Operating Temperature Range:-25°C to +125°C (Including self-temperature rise)



8. MSL : Level 1

6. Structural Drawing:



(Magnetic Shielded Type)

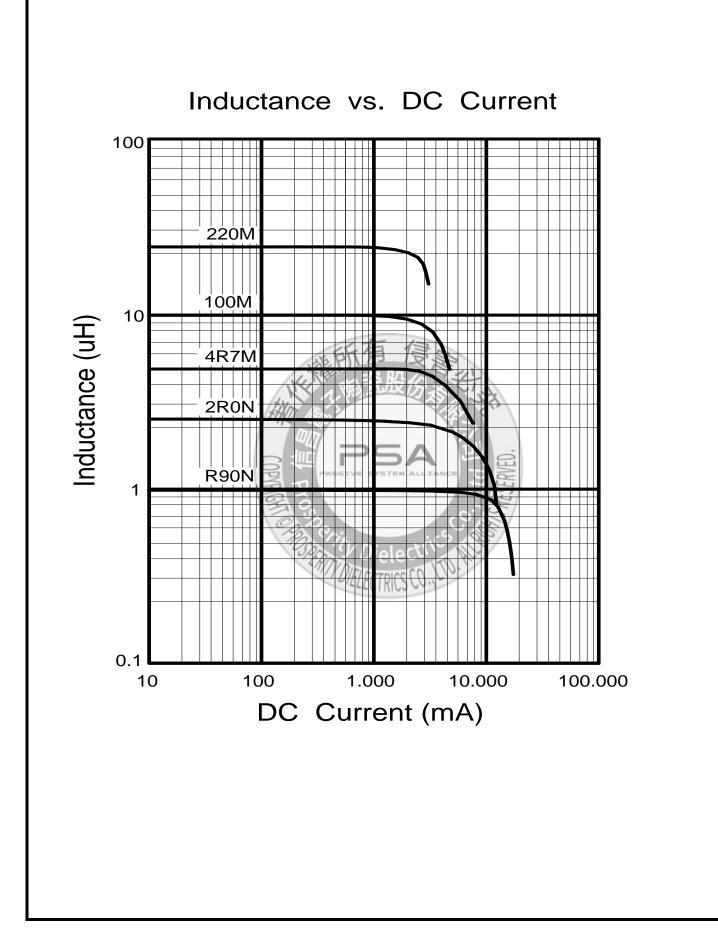
① Ferrite core.

- ② Winding wire
- ③ Over-coating resin.
- ④ External electrode
- ⑤ Base plating

Ni-Zn ferrite

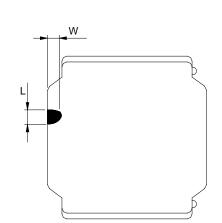
- Polyurethane-copper wire
- Epoxy resin, containing ferrite powder
 - Sn-Ag-Cu
 - Phosphor Bronze (using the Epoxy adhesive)

7. Electrical Curve :



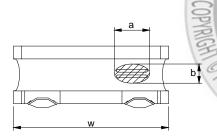
8. Core Chipping:

The appearance standard of the chipping size in top side, of bottom side ferrite Core is following dimension



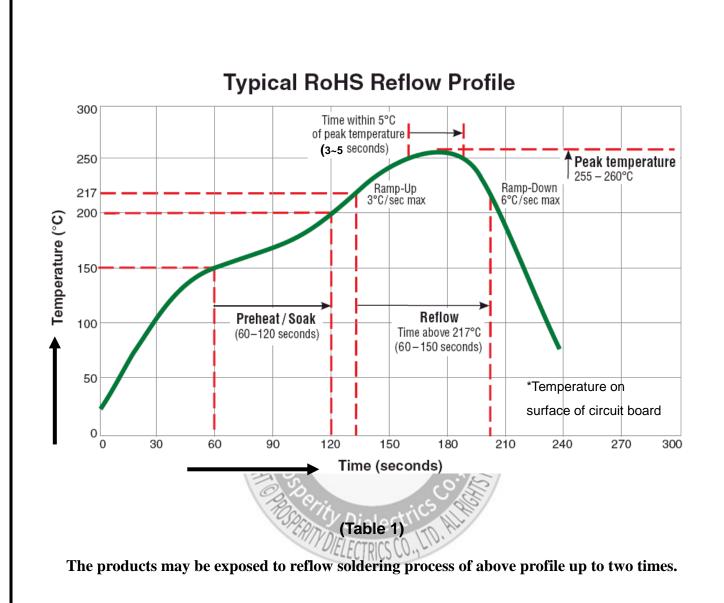
L	W
2.0mmMax.	2.0mmMax.

Exposed wire tolerance limit of coating resin part on product side Size of exposed wire occurring to coating resin is specified below.



 Width direction (dimension a): Acceptable when a<=w/2 Nonconforming when a>w/2
 Length direction (dimension b): Dimension b is not specified.
 When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

10. Reflow Profile Chart (Reference):



Test Item esistance to eflection	Standard No damage.	The test samples shall be soldered to the test board by the reflow soldering conditions show in Table 1. As illustrated below, apply force in the direction of the Arrow indicating until deflection of the test board Reaches to 2 mm.
		Force R230
		R5 45 ± 2 45 ± 2 0.8 1.4 0.8
		Land dimensions
		Test board size :100×40×10 Test board material I: glass epoxy-resin
dhesion of	Shall not come off PC	Solder cream thickness:0.1 Unit: mm The test samples shall be soldered to the test board
erminal lectrode	board	By the reflow soldering conditions shown in Table 1. 10 N, 5 s
	COPYRIGHT PROS	Applied force:10 N to X and Y directions Duration:5 s. Solder cream thickness:0,1 mm (Refer to recommended Land Pattern Dimensions Defined in "Precaution")
ody strength	No damage	Cample Gample
		ectrode board

Resistance to Vibration △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to the test baard by The reflow soldering conditions shown in Table 1. Then It shall be submitted to below test conditions Resistance to Soldering heat △L/L:within±10% No abnormality The test samples shall be soldered to the test baard by The reflow soldering conditions shown in Table 1. Then If shall be submitted to below test conditions Soldering heat △L/L:within±10% No abnormality The test sample shall be exposed to reflow oven at 230±5 deg C for 40 seconds, vitin peak temperature at 230±5 deg C for 40 seconds, vitin peak temperature at 230±5 deg C for 5 seconds, 2 times. Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Temperature Characteristics △L/L:within±20% No abnormality observed In appearance Measurement of inductance value at +20 deg C, change Rase within 25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rase shall be esployed to test board By the reflow soldering conditions shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples s	Test Item	Standard		Test method
In appearance Total Amplitude 1.5mm(May not exceed acceleration 196 m/S ²) Resistance to Soldering heat (Reflow) \[\L/L:within±10% No abnormality observed The test sample shall be exposed to reflow oven at 230±5 deg C for 49 seconds, with peak temperature at 260±5 deg C for 49 seconds, with peak temperature at 260±5 deg C for 5 seconds, 2 times. Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Temperature Characteristics \[\L/L:within±20% No abnormality observed In appearance Measurement of inductance value at +20 deg C, or 485 deg C. The test samples shall be placed at specified Show in below table. \[\L/L:within±20% No abnormality observed In appearance \[Measurement of inductance value at +20 deg C, With reference to inductance value at +20 deg C, With reference to inductance value at +20 deg C, change Rate shall be placed at specified Show in below table in sequence. In appearance The test samples shall be placed at specified Show in below table in sequence. In appearance The test samples shall be placed at specified Show in below table in sequence. In appearance Low Temperature life Test \[\L/L:within±10% No abnormality observed In appearance The test samples shall be coldered to the test board by the reflow soldering conditions shown in Table 1. Atter that, the test samples shall be placed at test Conditions as show in below table. Tempera			The reflow soldering	g conditions shown in Table 1.Then
In appearance 10th Antiplitude 196 m/S*). Sweeping Method 10Hz to 55Hz to 10 Hz for 1 min. Time Sweeping Method 10Hz to 55Hz to 10 Hz for 1 min. Time Resistance to Soldering heat \[\Delta Lu:within±10% No abnormality observed In appearance The test sample shall be exposed to reflow oven at 230±5 deg C for 40 seconds, with peak temperature at 260±5 deg C for 5 seconds, 2 times. Solder ability At least 90% of surface of terminal electrode is covered by new solder. Temperature Characteristics At least 90% of surface of terminal electrode is covered by new solder. Measurement of inductance shall be taken at temperature Characteristics Mo abnormality observed In appearance Multi-within±20% No abnormality observed In appearance Multi-within±10% No abnormality observed In appearance Multi-within±10% No abnormality observed In appearance Low Temperature life Test Low Temperature life Test Low Temperature life Test Au/L:within±10% No abnormality observed In appearance Multi-within±10% No abnorma		observed		
Time For 2 hours on each X,Y, and Z axis. Resistance to Soldering heat △L/L:within±10% No abnormality The test sample shall be exposed to reflow oven at 230±5 deg C for 40 seconds, with peak temperature at 260±5 deg C for 5 seconds, 2 times. Solder ability Observed In appearance The test samples shall be dipped in flux, and then Immersed in motion solder as shown in below table. Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in motion containing rosin 25% Solder Temperature Characteristics △L/L:within±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within 25 deg C to 485 deg C, change Rate shall be calculated. Thermal shock △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 1 4043 deg C 30±3 2 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 2 Room Temp		In appearance		196 m/S ²)
Resistance to Soldering heat (Reflow) △L/L:within±10% No abnormality The test sample shall be exposed to reflow oven at 230±5 deg C for 40 seconds, with peak temperature at 260±5 deg C for 5 seconds, 2 times. Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25% Temperature Characteristics △L/L:witthin±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within ±26 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock △L/L:witthin±10% No abnormality observed In appearance The test samples shall be polder do test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 40±3 deg C 30±3 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum Low Temperature life Test △L/L:witthin±10% No abnormality observed In appearance The test samples shall be placed to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.				
No abnormality 230±5 deg C for 40 seconds, with peak temperature at 260±5 deg C for 5 seconds, 2 times. Soldering heat No abnormality (Reflow) observed In appearance Test board thickness:1.0 mm Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Temperature Characteristics AL/L:within±20% Solder Temperature 245±deg C The maximum difficult observed In appearance Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. Thermal shock AL/L:within±10% Measurement of inductance value at +20 deg C, change Rate shall be calculated. The test samples shall be placed at specified Shown in Table 1. The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature life AL/L:within±10% Low AL/L:within±10% Temperature life AL/L:within±10% Temperature life AL/L:within±10% No abnormality observed Test samples shall be placed at test conditions shown in Table 1. The test samples shall be placed at test conditions shown in Table 1. <td></td> <td></td> <td>Time</td> <td>For 2 hours on each X,Y, and Z axis.</td>			Time	For 2 hours on each X,Y, and Z axis.
(Reflow) observed In appearance Test board thickness: 1.0 mm Test board material :glass epoxy-resin Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25% Temperature Characteristics △L/L:within±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within 25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature In appearance Time(min) 1 Low Temperature life Test △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. The test samples shall be placed at test Conditions so steps for 1 cycle Low Temperature life Test △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.	Resistance to	△L/L:within±10%	230±5 deg C for 40	seconds, with peak temperature at
Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25%. Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25%. Temperature Characteristics AL/L: within±20% No abnormality observed in appearance Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock AL/L: within±10% No abnormality observed in appearance The test samples shall be placed at specified Shown in below table in sequence. The test samples shall be explaced at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 11 Step Temperature Time(min) 11 Stat2 deg C 30±3 2 2 Room Temp 3 maximum 3 3 85±2 deg C 30±3 2 2 Room Temp 3 maximum 3 3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 2 1 At the test samples shall be placed at test Conditions as shown in below table.	Soldering heat	No abnormality	260±5 deg C for 5	seconds, 2 times.
Solder ability At least 90% of surface of terminal electrode is covered by new solder. The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25% Solder Temperature Characteristics \[\ldots\L_L:within±20% No abnormality observed In appearance \[\dots\L_L:within±10% No abnormality observed In appearance \[\dots\L_L:within±10% No abnormality observed In appearance The test samples shall be calculated. The test samples shall be calculated. The test samples shall be calculated. Solder Temperature 526 mm/s Thermal shock \[\dots\L_L:within±10% No abnormality observed In appearance The test samples shall be calculated. The test samples shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature 10 40±3 deg C 30±3 2 Time(min) 11 40±3 deg C 30±3 2 The test samples shall be soldered to the test board 2 3 85±2 deg C 30±3 4 Low Temperature life Test \[\ldots\L_Within±10% No abnormality observed In appearance The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test conditions as shown in below table.	(Reflow)	observed	Test board thicknes	s:1.0 mm
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covered by new solder. Solder Temperature 245±deg C Temperature Characteristics △L/L:within±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 -40±3 deg C 30±3 3 2 Room Temp 3 maximum 3 85±2 deg C 30±3 3 4 Room Temp 3 maximum 4 Room Temp 3 maximum 3 3 85±2 deg C 30±3 3 4 1 4	Solder ability		Immersed in molter	n solder as shown in below table.
Immersing Speed 25 mm/s Temperature Characteristics \u03c4 L/L:within±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock \u03c4 L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 440±3 deg C 30±3 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum Low Temperature life Test \u03c4 L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.				
Temperature Characteristics △L/L:within±20% No abnormality observed In appearance Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 -40±3 deg C 30±3 3 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum Low Temperature life Test No abnormality observed In appearance The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.		covered by new solder.		
Characteristics Adduction Range within -25 deg C to +85 deg C. No abnormality observed In appearance Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated. Thermal shock △L/L:within±10% No abnormality observed In appearance The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 -40±3 deg C 30±3 2 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum <td></td> <td>大道 一</td> <td>Immersing Speed</td> <td>1 25 mm/s</td>		大道 一	Immersing Speed	1 25 mm/s
Thermal shock △L/L:within±10% The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle Step Temperature Time(min) 1 -40±3 deg C 30±3 2 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 85±2 deg C 30±3 4 Room Temp 3 maximum 3 4 Room Temp 4 Room Temp 3 maximum 5 Conditions as shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. Temperature 7 Temperature <		No abnormality observed	Range within -25 de With reference to in	eg C to +85 deg C. Iductance value at +20 deg C, change
StepTemperatureTime(min)1-40±3 deg C30±32Room Temp3 maximum385±2 deg C30±34Room Temp3 maximum4Room Temp3 maximum4Room Temp3 maximumLow Temperature life Test^L/L:within±10% No abnormality observed In appearanceThe test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.Temperature-40±2 deg C	Thermal shock	△L/L:within±10% No abnormality observed	By the reflow solder The test samples sl Shown in below tab	ring conditions shown in Table 1. hall be placed at specified le in sequence.
StepTemperatureTime(min)1-40±3 deg C30±32Room Temp3 maximum385±2 deg C30±34Room Temp3 maximum4Room Temp3 maximum4Room Temp3 maximumLow Temperature life Test^L/L:within±10% No abnormality observed In appearanceThe test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.Temperature-40±2 deg C		Posti	Conditions of steps	for 1 cycle
Low AL/L:within±10% Temperature life AL/L:within±10% No abnormality The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. Temperature		ERITY		
Low A A Room Temp 3 maximum Low A Room Temp 3 maximum Low A Room Temp 3 maximum Temperature life A The test samples shall be soldered to the test board by No abnormality The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. Temperature -40±2 deg C				
Low A Room Temp 3 maximum Low A Room Temp 3 maximum Temperature life AL/L:within±10% The test samples shall be soldered to the test board by Test No abnormality The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. Temperature -40±2 deg C			2 Room	Temp 3 maximum
Low \[\L/L:within±10% Temperature life Test The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. Temperature life The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.				
Temperature life TestNo abnormality observed In appearanceThe reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table.Temperature-40±2 deg C			4 Room	Temp 3 maximum
	Temperature life	No abnormality observed	The reflow soldering After that, the test s Conditions as show	g conditions shown in Table 1. amples shall be placed at test n in below table.
l ime 500 +24/-0 h				
			lime	500 +24/-0 h

		Г	T
	Test Item	Standard	Test method
	Loading at high temperature life test	△L/L:within±10% No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table.
			Temperature 85±2 deg C
			Applied current (Refer to Page 2)
			Time 500+24/-0 h
ENVIRONMENT TESTS	Damp heat life test	△L/L:within±10% No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.
IENT			Temperature 60±2 deg C Humidity 90~95%RH
NNC		大陸	Time 500+24/-0 h
ENVIRG		AND ST	周载股份查测计
	Loading under Damp heat life test	△L/L:within±10% No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table. Temperature $60\pm 2 \deg C$ Humidity $90 \sim 95\%$ RH Applied current Rated current (Refer to Page 2)) Time $500+24/-0$ h

